

AN55662

Author: Ravi Prakash

Associated Part Family: STK14C88-3
CY14B256LA

Associated Application Notes: None

Application Note Abstract

This application note provides information for converting from STK14C88-3 parts to the CY14B256LA. It lists the parameter differences between the parts and the design considerations when converting existing applications from STK14C88-3 to CY14B256LA.

Introduction

Cypress CY14B256LA is a 3V, 32Kb x 8, 256 Kbit nvSRAM in 0.13u technology. This part is functionally equivalent to STK14C88-3 (0.8u) and is intended as a drop in replacement. This application note highlights the differences between the STK14C88-3 and the CY14B256LA and the parameters of significance that must be considered while migrating.

Overview

The following tables compare the features and parameters of the two parts. As shown in Table 1, the 256 Kbit nvSRAM is available in x8 configuration.

Table 1. Part Number Description

Description	Original Part Number	Replacement Part Number
32Kb x 8	STK14C88-3	CY14B256LA

Feature Set

Both parts share the same overall feature set and are available in the operation speed bins as follows.

Table 2. Feature Set Comparison

Feature Set	STK14C88-3	CY14B256LA
AutoStore	Available	Available
Software STORE	Available	Available
Hardware STORE	Available	Available
Software RECALL	Available	Available
AutoStore Inhibit	Available	Not Available
AutoStore Enable/Disable	Not Available	Available

Feature Set	STK14C88-3	CY14B256LA
Speed	-	25 ns
	35 ns	-
	45 ns	45 ns
STORE Cycles	1,000,000	200,000
Data Retention	100 years at 55°C	20 years at 85°C

Operating Temperature Range

While STK14C88-3 is available in both Commercial and Industrial temperature ranges, CY14B256LA is offered only in the Industrial temperature range.

Table 3. Operating Temperature Range Comparison

Operating Temperature Range	STK14C88-3	CY14B256LA
Commercial (0 to 70°C)	Available	Not Available
Industrial (-40 to 85°C)	Available	Available

Packages

CY14B256LA is pin compatible with STK14C88-3 and is available in the packages and pin configurations as follows.

Table 4. Packages Comparison

Package	STK14C88-3	CY14B256LA
32 SOIC	Available	Available
32 PDIP	Available	Not Available
48 SSOP	Not Available	Available
44 TSOPII	Not Available	Available

Parameters

The CY14B256LA is a drop in replacement for STK14C88-3 and requires minimum changes in the application board. However, the differences in parameters should be considered before replacing one part with the other. Table 5 lists the differences in parameters between STK14C88-3 and CY14B256LA.

Table 5. Parameter Comparison

Parameter	Description	Speed	STK14C88-3		CY14B256LA		Unit
			Min	Max	Min	Max	
DC Parameters							
V _{CC}	Power Supply		3.0	3.6	2.7	3.6	V
I _{CC1}	Average V _{CC} Current	25 ns		-		70	mA
		35 ns		52		-	
		45 ns		44		52	
I _{CC2}	Average V _{CC} Current during STORE			3		10	mA
I _{CC3}	Average V _{CC} Current at t _{RC} = 200 ns, V _{CC} typ, 25°C		9 (typ)		35 (typ)		
I _{CC4}	Average V _{CAP} Current during AutoStore Cycle			2		5	mA
I _{SB1}	Average V _{CC} Standby Current (Standby, Cycling Input)	35 ns		19	Not specified		mA
		45 ns		17			
I _{SB}	V _{CC} Standby Current			1		5	mA
V _{IH}	Input High Voltage		2.2		2		V
V _{OH}	Output HIGH Voltage			2.4 (I _{OUT} = -4 mA)		2.4 (I _{OUT} = -2 mA)	V
V _{OL}	Output LOW Voltage			0.4 (I _{OUT} = 8 mA)		0.4 (I _{OUT} = 4 mA)	V
V _{CAP}	Storage Capacitor		54 to 264		61 to 180		uF
AC Switching Parameters							
t _{OHA}	Output Hold After Address Change		5		3		ns
t _{LZCE}	Chip Enable to Output Active		5		3		ns
t _{LZWE}	Output Active After End of Write		5		3		ns
AutoStore / Power Up RECALL Parameters							
t _{HRECALL}	Power Up RECALL Duration			0.55		20	ms
t _{STORE}	STORE Cycle Duration			10		8	ms
t _{VSBL}	Low Voltage Trigger (V _{SWITCH}) to $\overline{\text{HSB}}$ low			300		25	ns
t _{RESET}	Low Voltage Reset Level			2.4	Not Applicable		V
t _{SWITCH}	Low Voltage Trigger Level		2.7	2.95		2.65	V
t _{DELAY}	Time Allowed to Complete SRAM Cycle		1,000			25	ns
V _{HDIS}	$\overline{\text{HSB}}$ Output Disable Voltage		Not specified			1.9	V
t _{LZHSB}	$\overline{\text{HSB}}$ To Output Active Time		Not specified			5	us
t _{HHHD}	$\overline{\text{HSB}}$ High Active Time		Not specified			500	ns
Software Controlled STORE/RECALL Cycle Parameters							
t _{HA}	Address Hold Time		20		0		ns
t _{RECALL}	STORE Cycle Duration			20		200	us
Hardware STORE Cycle Parameters							
t _{HLBL}	$\overline{\text{HSB}}$ LOW to STORE Busy			300		25 (t _{DELAY})	ns
t _{DHSB}	$\overline{\text{HSB}}$ To Output Active Time			700		25	ns

Critical Considerations

The impact of the differences in CY14B256LA with respect to the STK14C88-3 in existing applications are discussed as follows. Board designers are recommended to review the detailed datasheets when converting to the new part.

DC Parameters

The power supply design in most applications with STK14C88-3 would require no changes when replacing the nvSRAM with the CY14B256LA in spite of the higher values in the operating / higher standby current. The critical parameters to consider are the V_{CAP} and the V_{SWITCH}

V_{CAP}

While most of the differences do not impact the application, the difference in V_{CAP} is a critical consideration while converting from the older rev parts. V_{CAP} is the capacitor which provides the required charge for AutoStore to complete NV store of the SRAM data during power down. The required capacitor range is different in the two parts.

Table 6. V_{CAP} Comparison

Description	STK14C88-3	CY14B256LA
V_{CAP}	54 uF to 264 uF	61 uF to 180 uF

Therefore, any existing application using a capacitor value outside the overlapping range for the capacitor values needs to consider the impact of capacitor dimensions while changing to the new capacitor. Note: The capacitor range is the absolute value of the capacitor, net of tolerance.

V_{SWITCH}

The STK14C88-3 operates from 3V while the CY14B256LA operates from 2.7V. Hence the V_{SWITCH} levels are different.

Table 7. V_{CC} , V_{SWITCH} Comparison

Description	STK14C88-3	CY14B256LA
V_{CC}	3.0V to 3.6V	2.7V to 3.6V
V_{SWITCH}	2.7V to 2.95V	<2.65V

The difference in levels do not affect most applications except where the controller has operating range from 3.0V and above. In such applications, if CY14B256LA is used to replace STK14C88-3, at voltage levels below 3V, the controller could be tristated and hence CY14B256LA could write invalid data into the SRAM. This is because the CY14B256LA would be active up to 2.7V. In such application, it is necessary that the controller issues a reset when the V_{CC} crosses below 3V and remains LOW as long as the controller is inactive. This would initiate a Hardware STORE in the CY14B256LA and the nvSRAM outputs would be in tristate as long as the \overline{HSB} is held LOW by the controller.

AC Switching Parameters

There are a few minor differences in switching parameters between the CY14B256LA and the STK14C88-3, as listed in

the Table 5. However, these differences do not impact most applications. For replacing 35ns speed parts, choose the 25ns speed parts as replacement (since 35ns speed grade is not available in the CY14B256LA).

AutoStore/Power Up RECALL Parameters

$t_{HRECALL}$

The power up RECALL is much different in the CY14B256LA compared to the STK14C88-3 because of architecture differences.

Table 8. $t_{HRECALL}$ Comparison

Description	STK14C88-3	CY14B256LA
$t_{HRECALL}$	550 us	20 ms

This difference is not likely to affect applications since the initialization of the controller on the board happens at the same time. However, this should be taken into consideration when replacing the STK14C88-3 with CY14B256LA.

Software Controlled STORE/RECALL Cycle Parameters

The Software cycle parameter t_{RECALL} is different in CY14B256LA as described in the following section.

t_{RECALL}

Software RECALL time (t_{RECALL}) is higher in CY14B256LA.

Table 9. t_{RECALL} Comparison

Description	STK14C88-3	CY14B256LA
t_{RECALL}	20 us	200 us

This difference could require firmware change in the application to increase the wait state when software RECALL is initiated.

Software Sequence

The CY14B256LA is designed to be compatible with STK14C88-3 in the software sequence modes. Hence, the same Software STORE and RECALL address sequences in STK14C88-3 works in CY14B256LA, requiring no firmware change.

Hardware STORE Cycle Parameters

The Hardware STORE parameters are much improved in the CY14B256LA. The improvements are listed under the following section on [Details of Improvement](#). No changes are required in applications.

AutoStore Inhibit

The STK14C88-3 has the AutoStore Inhibit feature and the CY14B256LA has AutoStore Disable mode. These two provide the same result of AutoStore disable but are done by different means – hardware in STK14C88-3 and software in CY14B256LA.

To disable AutoStore in STK14C88-3, the power is connected to the V_{CAP} pin and the V_{CC} pin is grounded (or left open). This cannot be done in CY14B256LA. For proper operation of the device, in CY14B256LA, power is connected to the V_{CC} pin only. However, AutoStore disable is more easily done through simple software sequence. Therefore, if the STK14C88-3 is replaced in an application where AutoStore has been disabled, then the layout has to be modified to connect the power to the V_{CC} pin and a software sequence has to be used to disable AutoStore function followed by a Software STORE, the first time the board is powered up.

STORE Cycles

The NV STORE cycles endurance in CY14B256LA is lower than the endurance in the older 0.8u technology. However, this would not affect most applications since all nvSRAMs have infinite read/write endurance and the NV STORE cycle happens only during power down or during Software STORE. For example, if a system is powered down 10 times a day, then the NV STORE endurance is reached in 54 years in CY14B256LA.

Data Retention

The Data Retention in 0.13u part is vastly improved from the older technology part. The CY14B256LA has a data retention of 20 years at 85°C against the STK14C88-3 data retention of 100 years at 55°C. This translates to over 4 times improvement in data retention at the same temperatures.

Details of Improvement

Hardware STORE Related Improvements

HSB pin (Hardware STORE Busy Indication/Hardware STORE Initiation)

The $\overline{\text{HSB}}$ pin of the nvSRAM is an open drain I/O pin used to indicate or initiate a STORE operation. When a STORE operation is in progress, nvSRAM pulls the $\overline{\text{HSB}}$ pin low to indicate that the device is busy and cannot be accessed for read/write operation. During normal operation, the $\overline{\text{HSB}}$ pin can be pulled low to initiate a Hardware STORE operation.

As shown in Table 5, several timing parameters related to the $\overline{\text{HSB}}$ pin input and output have changed from STK14C88-3 to CY14B256LA. All of these changes are improvements from the original part specification and should be considered as added benefits in your system while converting to the new part number.

Write Latch: When a write operation is done, a 'write latch' is set internally. When $\overline{\text{HSB}}$ is pulled low, nvSRAM checks this write latch before initiating a STORE. This is done to prevent any unnecessary loss of endurance cycles.

t_{DELAY}

If a write latch is set and the $\overline{\text{HSB}}$ pin is pulled low, STK14C88-3 enables 1 us time for write operations to complete before STORE operation begins and reads and

writes are inhibited. This potentially enables inadvertent data to be written to the nvSRAM during the t_{DELAY} duration.

In CY14B256LA, the t_{DELAY} parameter enables only one write cycle time for any ongoing write to complete after $\overline{\text{HSB}}$ pin is pulled low. This improvement provides better security from inadvertent write operations.

Also, if $\overline{\text{HSB}}$ pin is pulled low externally for a minimum of t_{PHSB} time on CY14B256LA, the output driver of $\overline{\text{HSB}}$ pin pulls the pin low only indicating a STORE operation within 25 ns (t_{DELAY}). This parameter for $\overline{\text{HSB}}$ low to STORE busy is not specified in the STK14C88-3. (See Figure 1 and Figure 2)

$\overline{\text{HSB}}$ LOW when write latch not set:

If no writes are performed since the last STORE/RECALL operation, STORE operation does not start when $\overline{\text{HSB}}$ is pulled low. However, the $\overline{\text{HSB}}$ pin is still internally pulled low for 1 us (t_{DELAY}) time in the STK14C88-3 device.

CY14B256LA device does not pull the $\overline{\text{HSB}}$ pin low internally if write latch is not set.

Figure 1. STK14C88-3: AC Parameters Related to $\overline{\text{HSB}}$

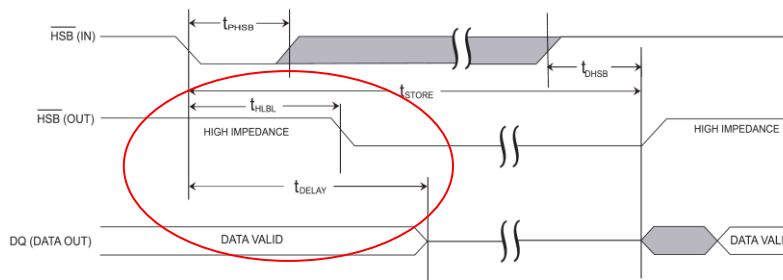
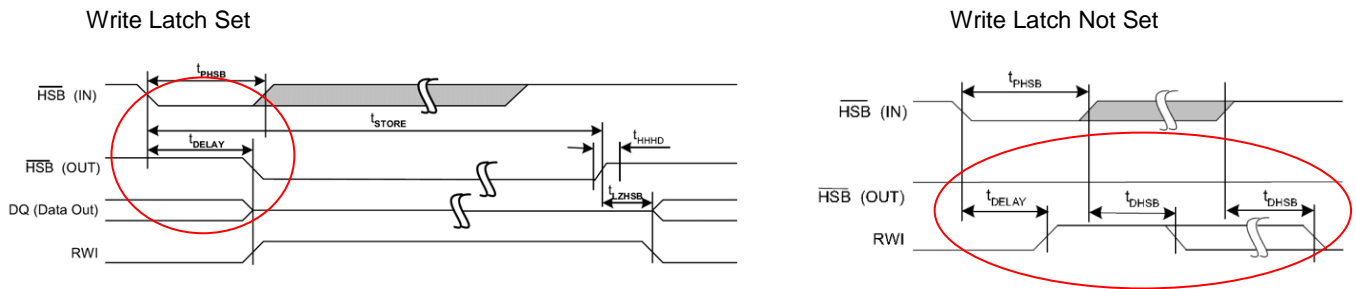


Figure 2. CY14B256LA: AC Parameters Related to $\overline{\text{HSB}}$



Power Up Recall Related Improvements

Additional parameters are specified in CY14B256LA such as $\overline{\text{HSB}}$ Output Disable Voltage (V_{HDIS}), $\overline{\text{HSB}}$ To Output Active Time (t_{LZHSB}), and $\overline{\text{HSB}}$ High Active Time (t_{HHHD}) which helps in system design. Refer to Figure 3 and Figure 4 for the definition of the additional specs in power up. Also, note that $\overline{\text{HSB}}$ remains low until the end of the power up in the new part. This would guard against the system inadvertently thinking the part has completed the boot up prior to real completion.

Figure 3. STK14C88-3: Power Up Recall

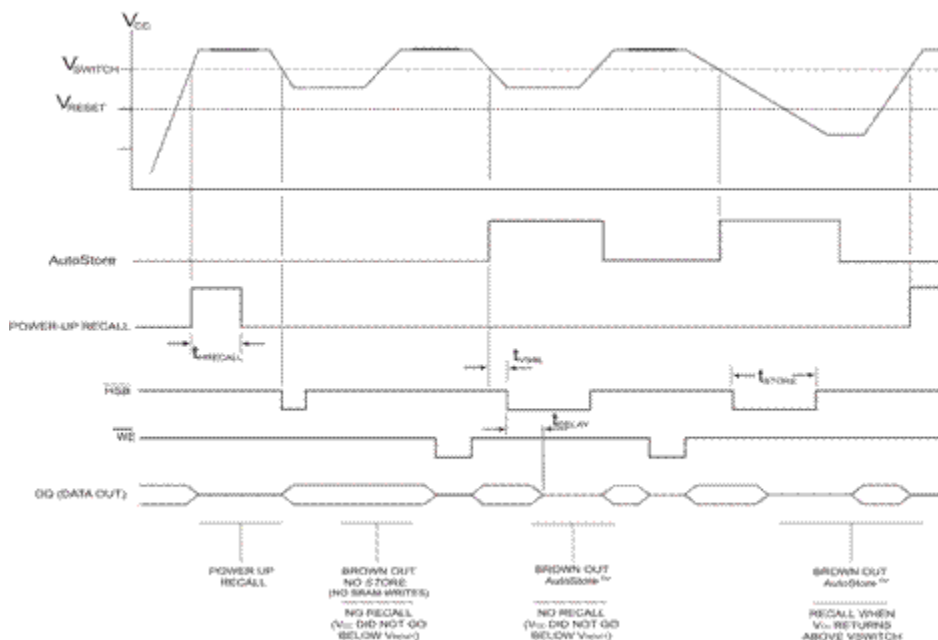
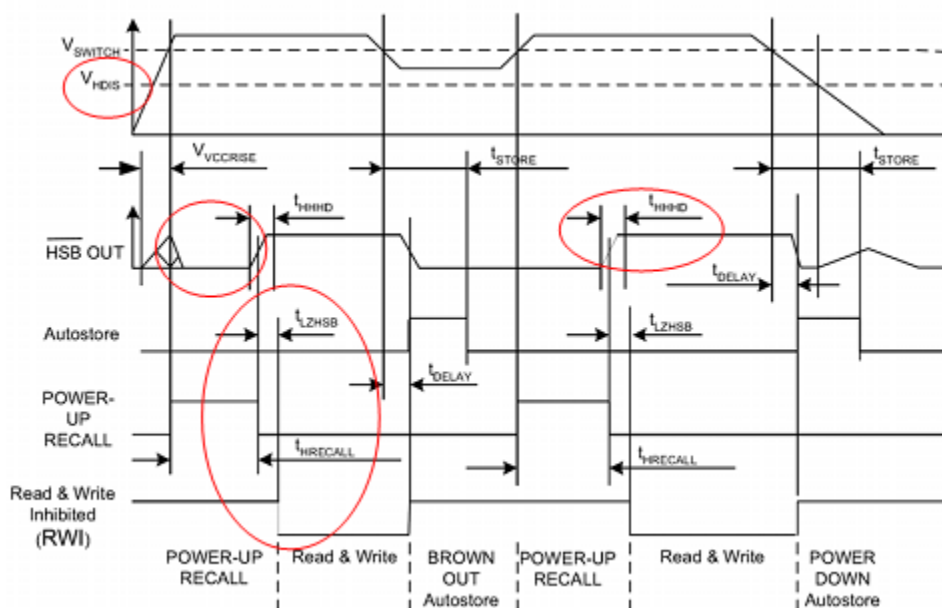


Figure 4. CY14B256LA: Power Up Recall



Summary

The application note discusses the differences between CY14B256LA in the latest 0.13u technology and STK14C88-3 in the 0.8u technology. Several parameters related to HSB and power up have improved/specified in the new device enabling faster device response, greater data security and ease of design.

CY14B256LA is pin compatible and can replace the STK14C88-3 device with no changes or minimum changes to the firmware. The value of VCAP in the existing design needs to be considered while replacing the part.

Document History

Document Title: Converting from STK14C88-3 to CY14B256LA

Document Number: 001-55662

Revision	ECN	Orig. of Change	Submission Date	Description of Change
**	2773126	PSR	10/01/09	New Spec.

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Cypress Semiconductor
 198 Champion Court
 San Jose, CA 95134-1709
 Phone: 408-943-2600
 Fax: 408-943-4730
<http://www.cypress.com/>

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